

HOW TO REMOVE FLUX RESIDUES FROM PCBAS



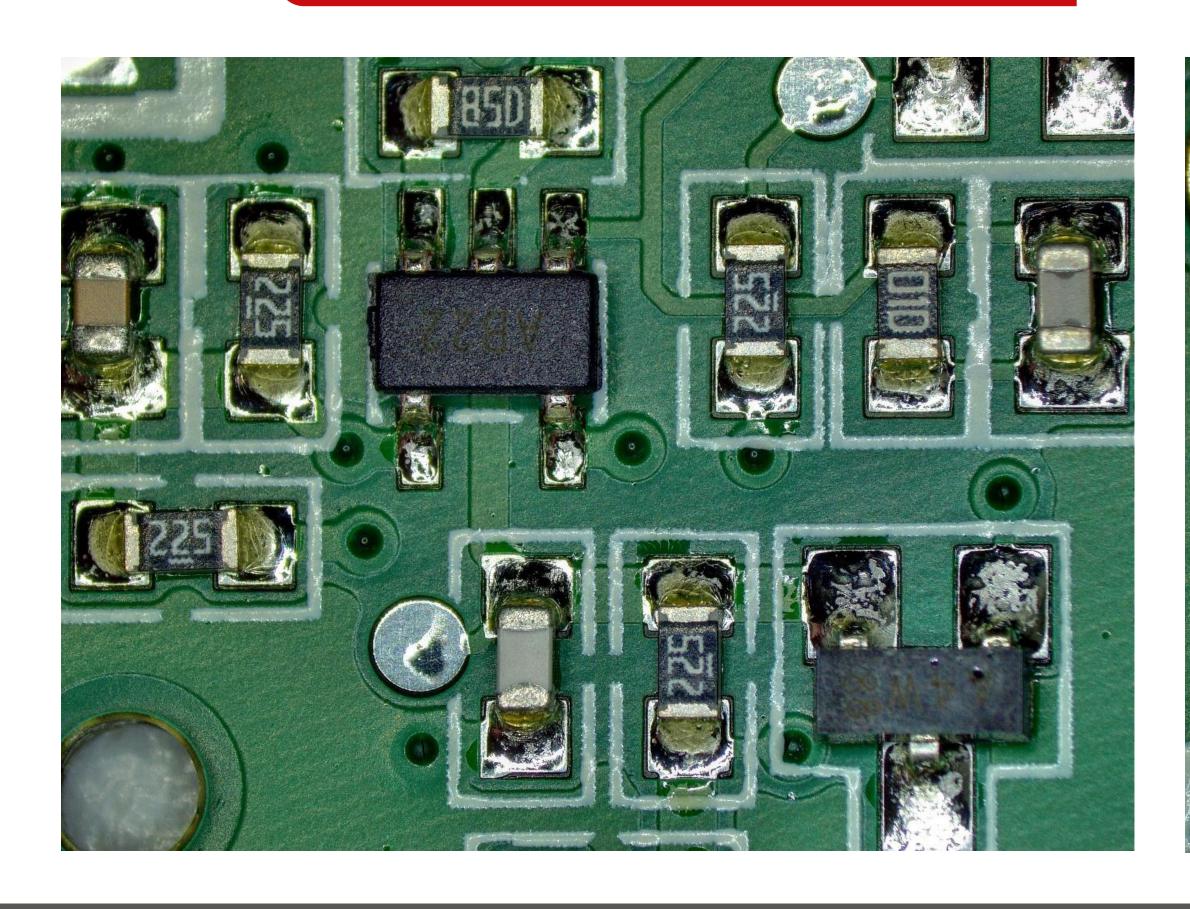
The customer uses KOKI soldering paste. Its flux residues are very difficult to remove from PCBAs.
Furthermore, the customer truly cares about the high quality of the production, so they tear off the components from PCBAs to be sure about the perfect cleanliness even under the components. This is a technically demanding application.

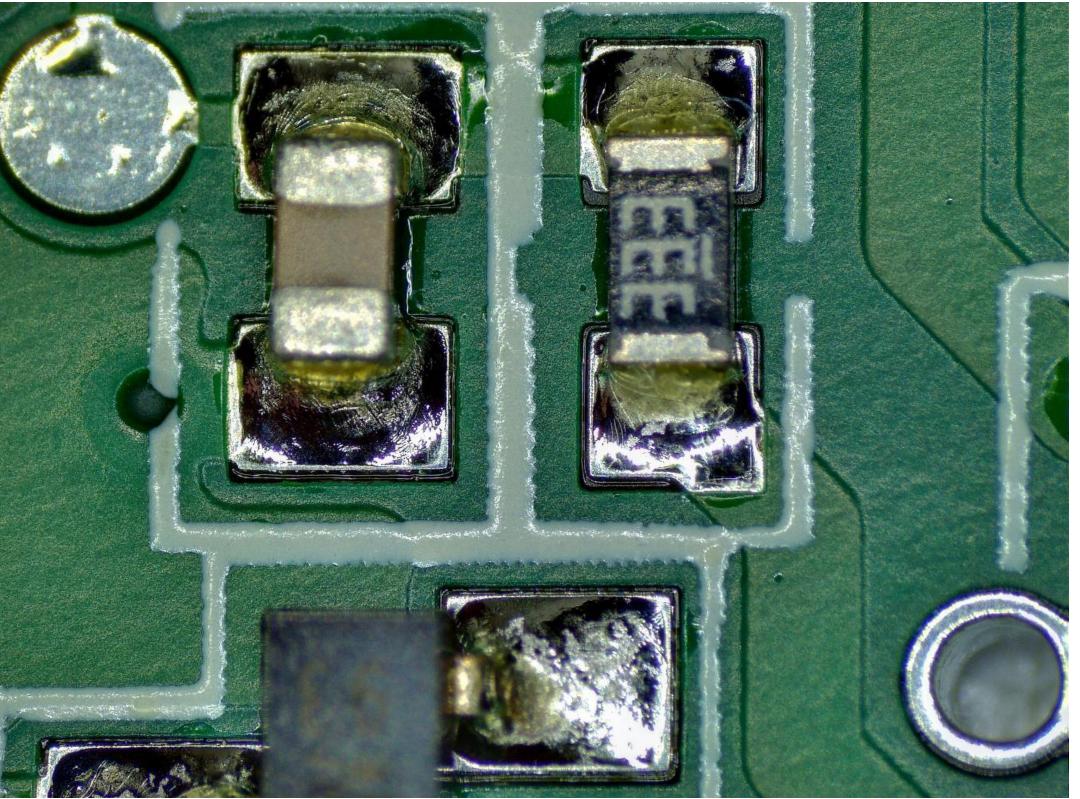


We tested how to clean flux residues from PCBs after soldering process.

PCBAs Before Cleaning

Type of Solder Paste: KOKI S3X58-M500C







COMPLETE CLEANING SOLUTION BY DCT

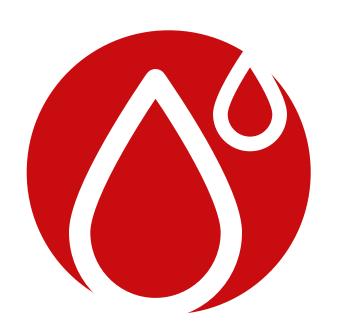
Water-based cleaning agent Decotron® CP384



Cleaning system Injet® 888 CRD with the technology of vertical high-pressure Spray-In-Air







RECOMMENDED CLEANING PROCESS

Cleaning:

Decotron® CP384 / 15 min / 50°C

Drip: 180 s

Rinsing: DI Water / 5 min / 25°C

Drip: 90 s

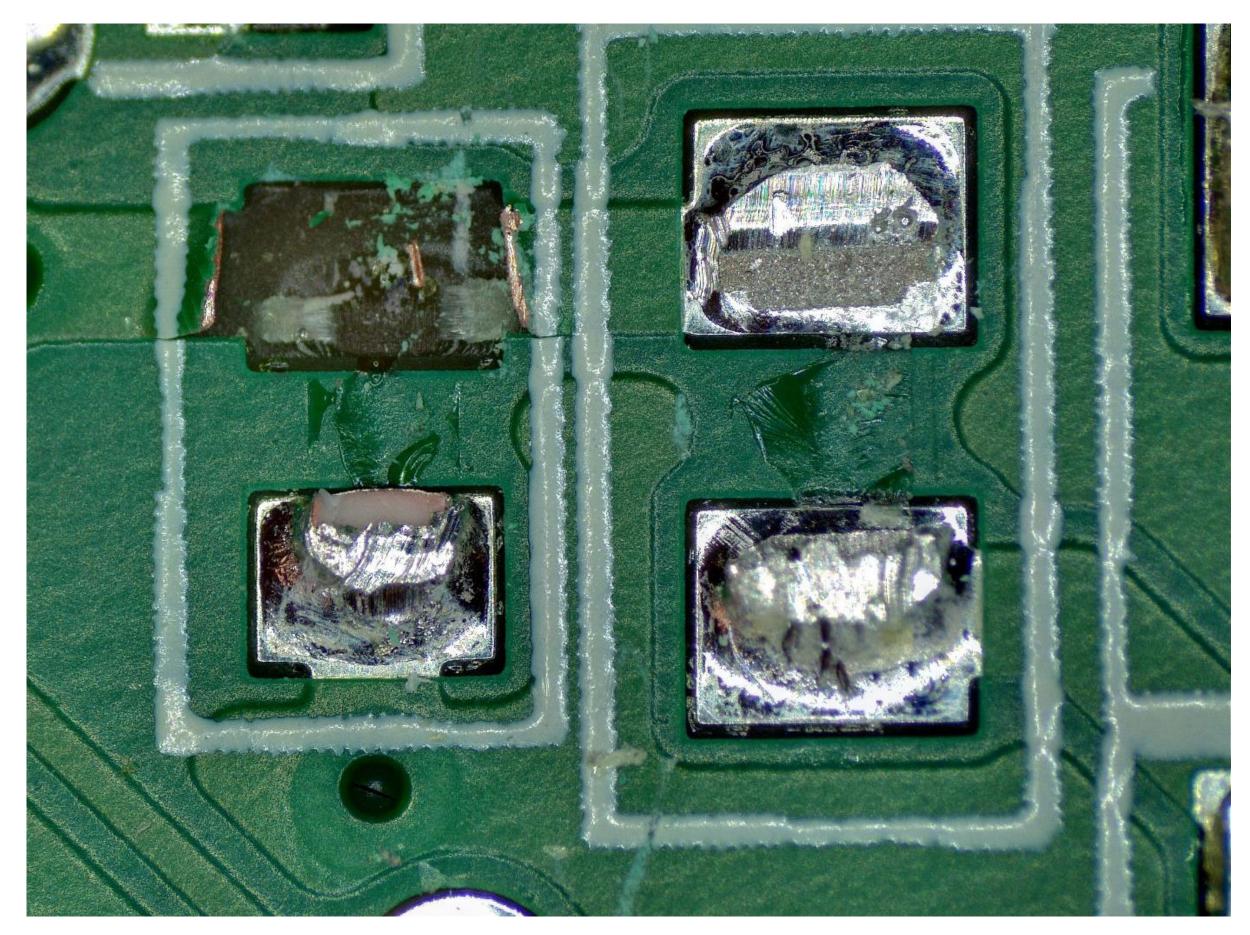
Drying: hot air / 10 min / 80°C

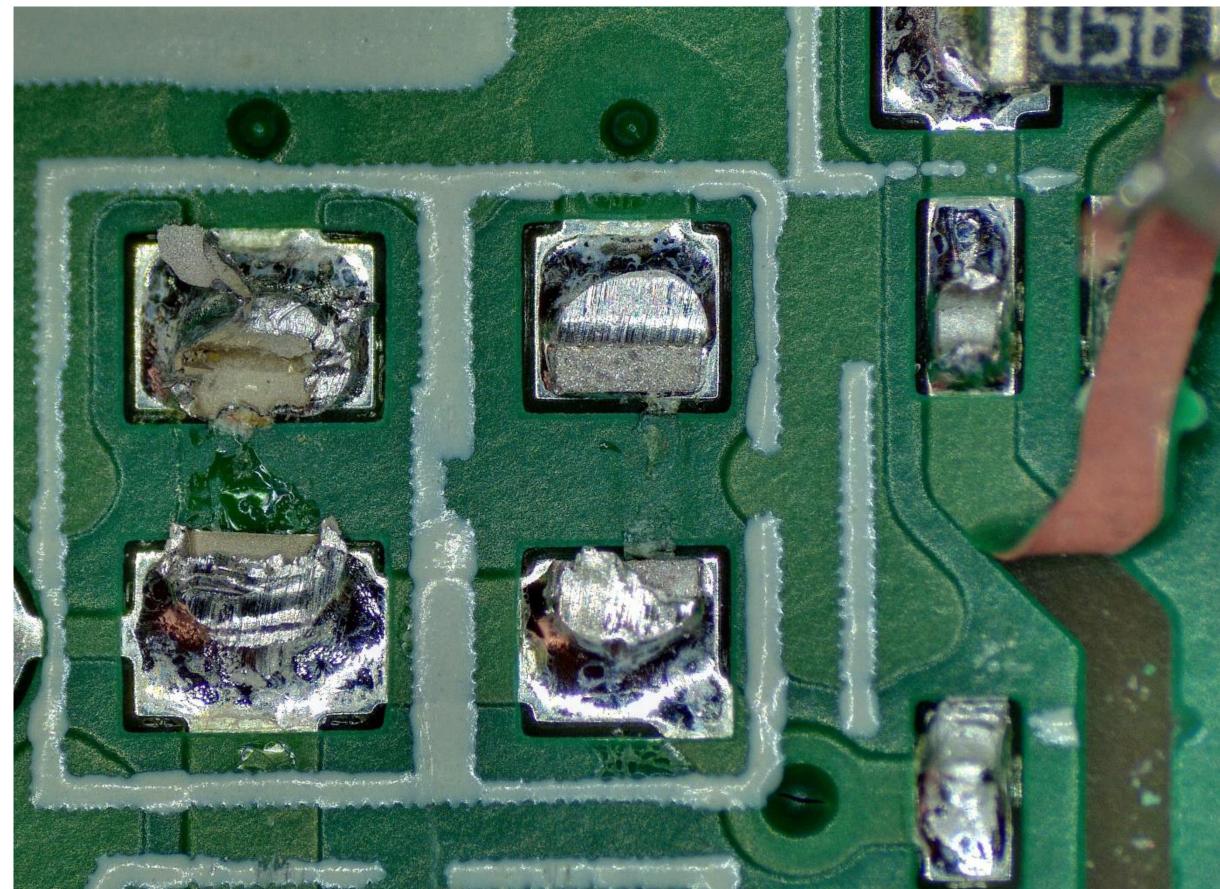


The cleaning process is incredibly fast thanks to our complete cleaning solution.

Only 15 minutes has taken to perfectly clean solder paste KOKI S3X58-M500C from PCBs after the soldering process!

Example of Insufficient Cleaning Time (1 min.)







RECOMMENDED CLEANING AGENT





Technical data sheet



- Water-based cleaning agent
- Determined to clean misprints and flux residues after soldering
- Provides effective cleaning under components
- Ready-mix, intended for direct use

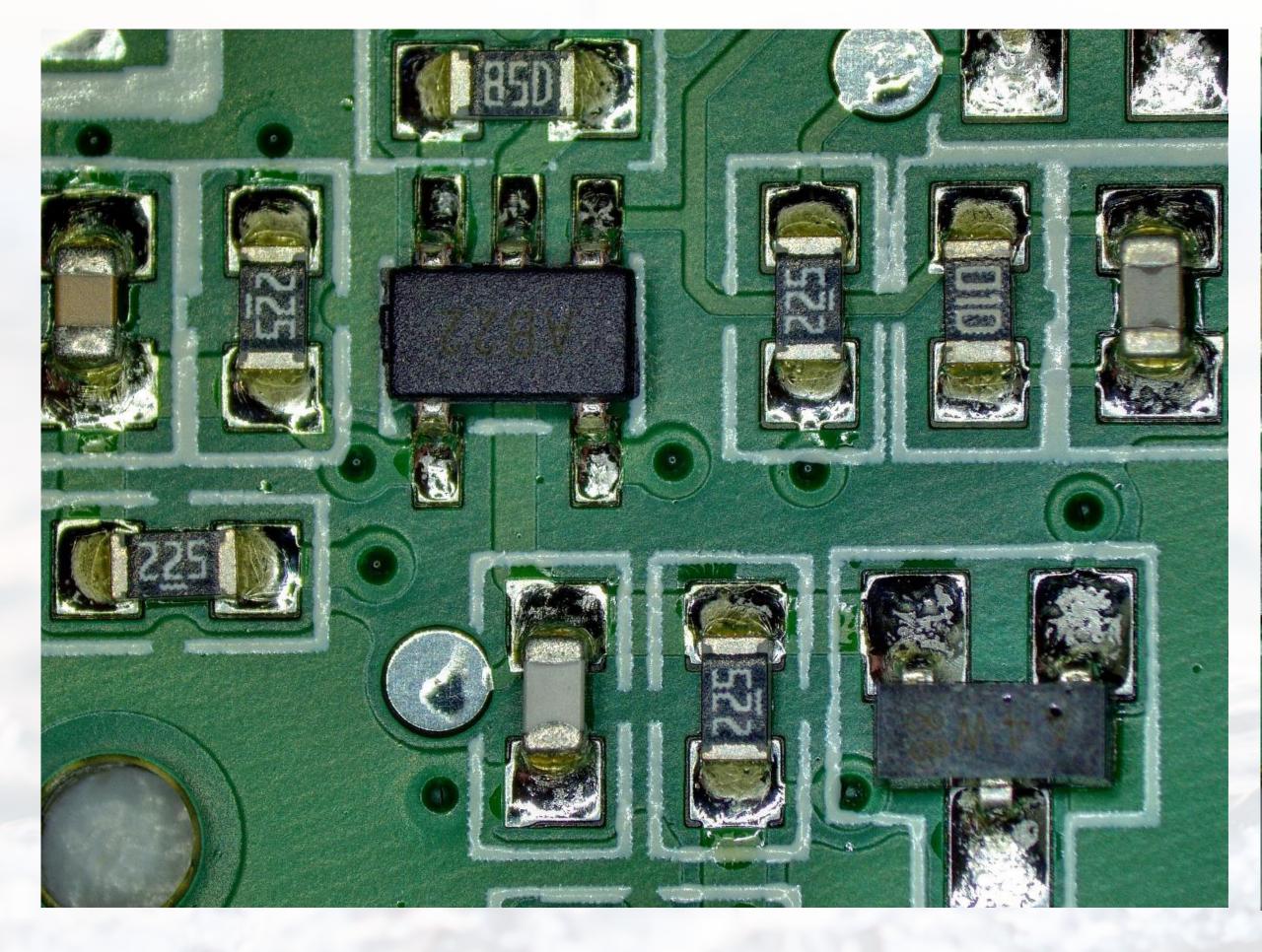


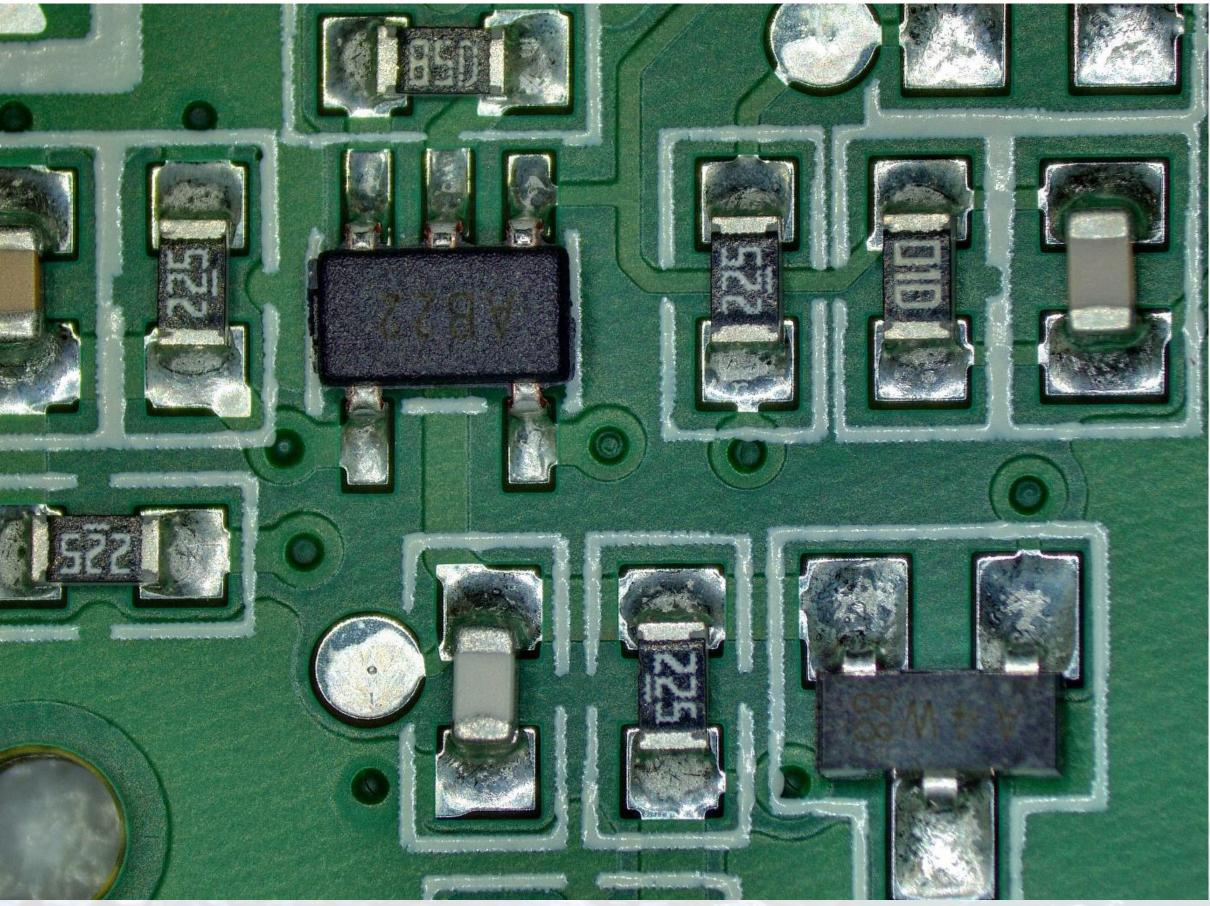
New cleaning fluid **Decotron**® **CP384**was successfully introduced to several
customers, who struggled to clean
flux residues of solder paste **KOKI S3X58-M500C from PCBAs**. The
cleaning process including also our
cleaning machine **Injet**® **888 CRD** is
able to clean flux residues even
under the components!

BEFORE Cleaning ->

AFTER Cleaning

with Decotron® CP384

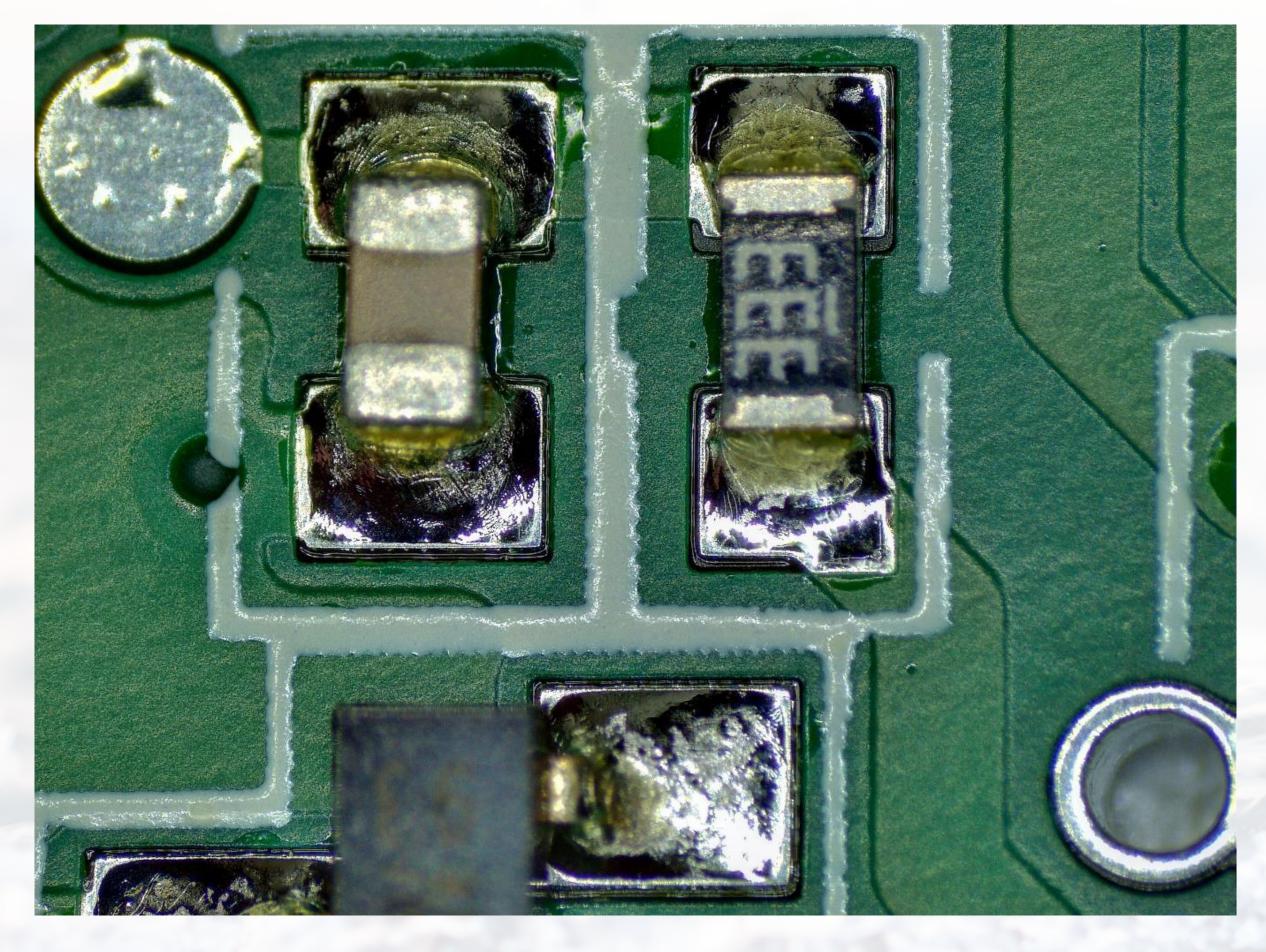


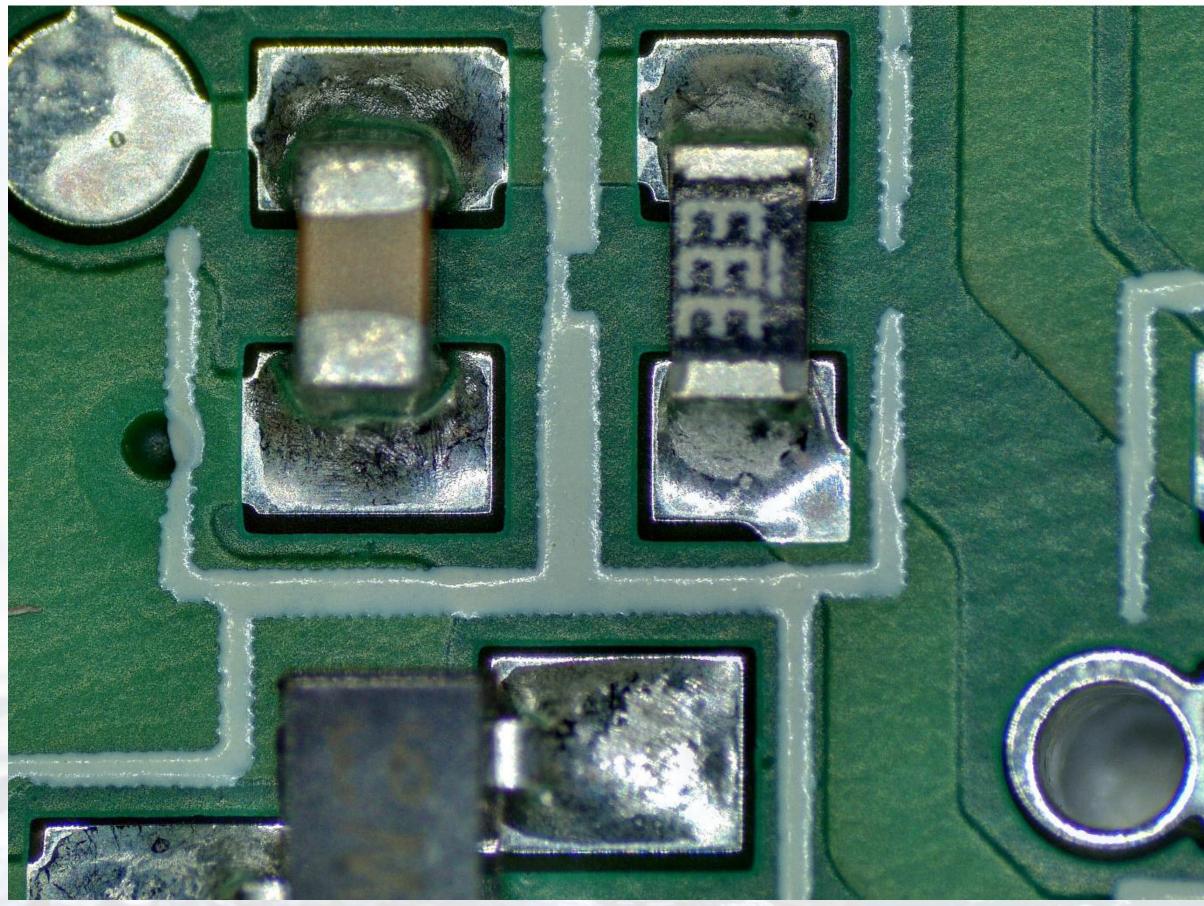


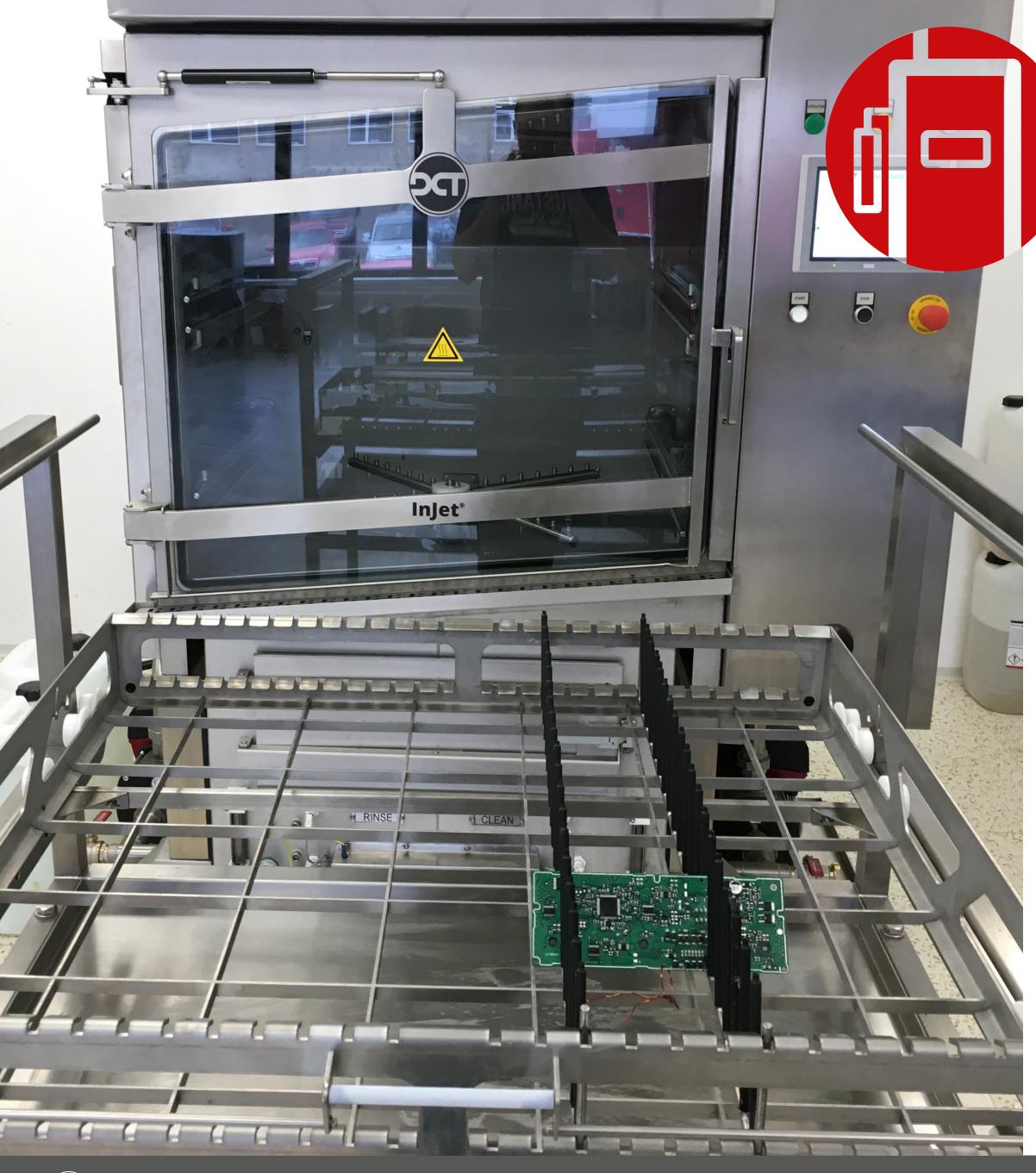
BEFORE Cleaning ->

AFTER Cleaning

with Decotron® CP384







RECOMMENDED CLEANING SYSTEM

Injet® 888 CRD

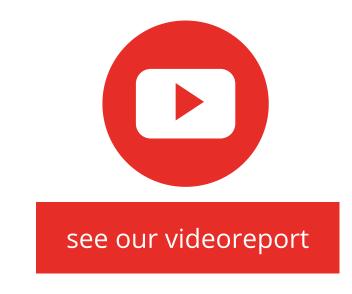
with horizontal high-pressure Spray-In-Air technology

*** REFLOW and SOLDERING PARTS cleaning

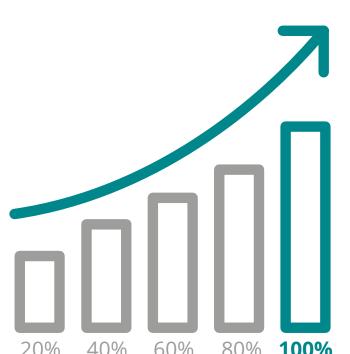
PCB cleaning **

STENCIL, MISPRINT, SQUEEGEE cleaning









RESULTS OF TESTING

Success rate: 100%

Because the customer uses a competitor's cleaning system with 1 chamber only, we needed to face issues connected with high cross-contamination in this process. We managed these issues by the **development of a new customized cleaning agent** for this customer. However, we would recommend implementing the cleaning system InJet® 388 TWIN CRRD in the future, which offers the minimum cross-contamination thanks to its unique 3-chamber layout.